Soft feeling, low contact resistance metal contacts and round terminals with excellent PC board mounting performance







■ Typical Specifications

Items	Specifications
Rating (max.)	50mA 16V DC
Rating (min.)	10μA 1V DC
Initial contact resistance	100mΩ max.
Travel (mm)	1.3

■ Product Line

Product No.	Operating	Operating direction	Operating life	Rubber color	Minimum order unit (pcs.)	
Floudet No.	force	Operating direction	(5mA 5V DC)	nubbel coloi	Japan	Export
SKPLAGD010	1.57N			Gray		
SKPLAKD010	1.96N	Top push	100,000 cycles	Green	2,700	2,700
SKPLAFD010	2.45N			Yellow		

Packing Specifications

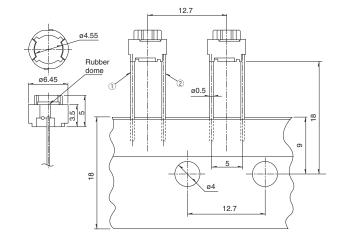
Radial taping

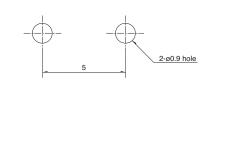
Number of packages (pcs.)			Export package measurements
1 box	1 case / Japan 1 case / export packing		(mm)
2,700	27,000	27,000	353×716×244

Unit:mm Box size

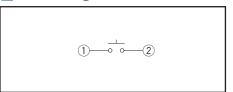
Dimensions

Unit:mm PC board mounting hole dimensions (Viewed from switch mounting face) Style





Circuit Diagram



Using a 1.6mm thick PC board is recommended.



					Soft Fee	ling Type			
	Type	Snap-in			Surface Mount		Ra	Radial	
	Series	SKEG	SKEG	SKPF	SKPM	SKPG	SKPR	SKPL	SKPD
	Photo						9		
	Features	_	_	High operation force Long travel	Low contact resistance	_	High operation force Low contact resistance	Round terminal Low contact resistance	_
\	Water-proof	_	_	_	_	_	_	_	_
	Dust-proof	_	_	_	_	_	_	_	_
ı	P standard	_	_	_	_	_	_	_	_
Operati	Top push	•	_	•	•	•	•	•	•
direction	Side push	_	•	_	_	_	_	_	_
	W		7.5	8	5.9	6.6	7.5	0.15	
Dimension (mm)		- □6	9.9	9	6	6.3	7.8	φ 6.45	□7.8
(11111)	Н	See the relevant pages for respective product descriptions	7.3	10	Ę	5	6.5	5	See the relevant pages for respective product descriptions
	Contact		Carbon		Silver	Carbon	Sil	ver	Carbon
Operation force coverage	2N to 3N	1	1	1	1	1	‡	1	Ţ
Т	ravel (mm)		1	See the relevant pages for respective product descriptions	1.	.3	1	1.3	See the relevant pages for respective product descriptions
Gro	ound terminal	_	_	_	_	_	_	_	_
Opera:	ting temperature range	-20℃ t	o +70℃			-40°C t	to +90°C		
Au	tomotive use	_	_	•	•	•	•	•	•
	Life Cycle	* 2	* 2	*2	*3	*3	*3	* 2	* 2
	Rating (max.) (Resistive load)	5mA 12V DC 50mA 5mA 50mA 16V DC 16V DC				5mA 12V DC			
Electrical	Rating (min.) (Resistive load)		10μA 1V DC						
performance	Insulation resistance	50MΩ min. 100V DC 1min. 50MΩ min. 100V DC 1min. SKPDAF 100V DC 1min. 100V DC 1min.				50MΩ min. 100V DC 1min. SKPDAF: 100MΩ min. 100V DC 1min.			
	Voltage proof		OF OVER A CENTER 100V ACE Imin.						
Durability	Vibration		10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2 hours respectively						
Durability	Lifetime	Shall be in accordance with individual specifications.							
	Cold	-30℃ 96h -40℃ 96h		-40℃ 1,000h	-40℃ 96h	-40℃	1,000h	-40℃ 96h	
Environmental performance	Dry heat	80°C 96h 90°C 1,000h 90°C 96h 90°C 1,000h		,000h	90℃ 96h				
	Damp heat				60°C, 90 to 95%RH 96h				
	Page	25	51	253	254	255	256	257	258

W : Width. The most outer dimension excluding terminal portion. D : Depth. The most outer dimension excluding terminal portion.

Notes

H : Height. The minimum dimension if there are variances.

^{1.} The automotive operating temperature range to be individually discussed upon request.

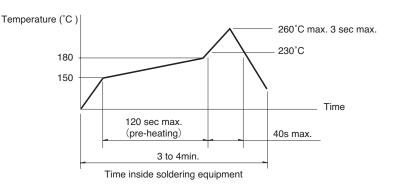
^{2. •} Indicates applicability to all products in the series, while O indicates applicability to some products in the series.

TACT Switch™ Soldering Conditions

Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
 - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others.
 The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

	3.
Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKQJ, SKQK, SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

Manual Soldering

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

Notes

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)

